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| INFORMATION DISCLOSURE STATEMENT <div style="position: relative; height: 100px;"> # 2 </div> | | | | Atty. Docket No.: 1065-US | | Serial No.: Unassigned | |
| | | | | Applicant: Payer, et al. | | Group: Unassigned 2539 | |
| | | | | Filing Date: Unassigned | | Examiner: Unassigned | |

JC971 U.S. PAT. 09/885226
 06/20/01

| U.S. PATENT DOCUMENTS | | | | | | | |
|-----------------------|----|-----------------|------------|-------------------|-------|----------|----------------------------|
| Examiner Initial | | Document Number | Date | Name | Class | Subclass | Filing Date if appropriate |
| <i>TC</i> | AA | 5,996,221 | 12/07/1999 | Chirovsky, et al. | 29 | 840 | <i>25</i> |
| | AB | | | | | | |
| | AC | | | | | | |
| | AD | | | | | | |
| | AE | | | | | | |
| | AF | | | | | | |

| FOREIGN PATENT DOCUMENTS | | | | | | | | |
|--------------------------|----|-----------------|-------------|---------|-------|----------|-------------|----|
| | | Document Number | Date | Country | Class | Subclass | Translation | |
| | | | | | | | Yes | No |
| <i>TC</i> | AG | 98/53355 | 26 NOV 1998 | WO | G02B | 7/182 | | |
| | AH | | | | | | | |
| | AI | | | | | | | |

| OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.) | | |
|--|----|---|
| <i>TC</i> | AJ | Luk, C.F.; Chan, Y.C.; and Hung, K.C., "Development of Gold to Gold Interconnection Flip Chip Bonding for Chip on Suspension Assemblies," 2001 Electronic Components and Technology Conference. |
| | AK | |
| | AL | |
| | AM | |
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| Examiner T C Patel | Date Considered 10/2/02 |
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Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.